Cleaning Processes across NASA Centers

Cleaning:

All significant surfaces of the hardware must be pre-cleaned to remove dirt, grit, scale, corrosion, grease, oil and other foreign matter prior to any final precision cleaning process. Metallic parts shall be surface treated (cleaned, passivated, pickled and/or coated) as necessary to prevent latent corrosion and contamination. ("Process Specification for Cleaning of Hardware"/PRC-5001, Rev. E [JSC], page 7)

Stages of Cleaning Processes:

- 1. Pre-cleaning/surface cleaning
- 2. Inspection
- 3. Precision cleaning
- 4. Verification
- 5. Handling
- 6. Drying
- 7. Final Packaging

Chemicals for Cleaning

- Detergent/Degreaser *
- Caustic Acid (Oakite HD 126) *
- Rinse Water (RO Water) *
- Mild Alkaline (Oakite 31) *
- Oakite Liquid Rustripper *
- Oakite Rustripper *

Equipment for Cleaning Processes

- Personal Protective Equipment
- "Bunny suits" to protect clean rooms from outside contaminants
- Vats/Tanks
- Sandblaster machines *
- Jet spray washers *
- Heated pressure washers *

Locations for Cleaning

- Clean flow benches *
- Clean rooms
- High bay areas *
- Onsite

Types of Items Cleaned

- Components
- Tank Lines
- Pressure Vessels
- Tools
- Personal Protective Equipment

^{*} Primary Source: WSTF

Clean Rooms/Clean Areas/Location Cleaning

Clean Roc	ms/Clean Areas/Location Cleaning		
	WSTF	MSFC	SSC
Clean Rooms	Class 10,000 clean room (180 sq ft) Function tests of components up to 11,000 psi: valves, regulators, and intensifiers Precision clean cryogenic pumps Precision clean relief valves, high pressure compressors, and other components Class 10,000 clean room (140 sq ft) Precision clean of all clean room garments used at WSTF Class 100 clean room (600 sq ft) Final verification and cleanliness of components up to 50 A Capable of handling flight hardware Class 100 Flight Hardware clean room (400 sq ft) Pilot Operating Valves (POV), Veneer Direct Acting Valves (DAV), Oxygen Regenerating Compressor Assembly (ORCA), Hydrogen Flow Control Valve (HFCV) Class 100 reassembly room (300 sq ft) Function test of components up to 20,000 psi	Class 100,000 clean room (4,000 sq ft) Precision Cleaning facility cleans valves components, tubing, piping and misc hardware. Precision cleaning of Project hardware for ECLSS, MSRR, G-LIMIT and others. Class 10,000 clean room (4500 sq ft) Precision Cleaning facility cleans valves components, tubing, piping and misc hardware. Class 30,000 clean room (432 sq ft) Packaging and inspection for Precision Cleaning Black and white light inspection Class 100,000 clean room Precision Assembly (2000 sq ft) Precision Assembly of Project hardware. ECLSS: Rack, OGA, ORU, UPA, DA, Pump MSRR G-LIMIT Class 100 Flow bench NVR and Particulate analysis Small item assembly	Class 10,000 clean room (1500 sq ft) Function tests of components up to 6,500 psi. Precision clean components, tubing, and fittings
Clean Areas	 Several Class 100 Flow benches Bubble Point Tester for filters Heise gauge-cleaning station up to 50,000 psi 	 Class 300,000 Clean Areas Dry Film Lube, Precision Cleaning, MLI Blanket Fabrication 	 Anteroom (450 sq ft)with Class 100 Flow bench Test Cell – functional testing of precision cleaned components to 15,000 psi
Location Cleaning	High Bay Area • 6,000 gallon tanker trucks • Large vessels • 4-inch convoluted hoses • Long pipes • Pressure vessels • Chambers	Location Cleaning outsourced	High Bay Area Convoluted hoses Long pipes Pressure vessels
Other	 Vats (for Component Cleaning) Detergent/Degreaser (Simple Green) – Vat size 2.5' L x 2.5' W x 2 'D Caustic Acid (Oakite HD 126) – Vat size 2.5' L x 2.5' W x 2 'D Rinse Water – (RO water) – Vat size 2.5' L x 2.5' W x 2 'D Mild Alkaline (Oakite 31) – Vat size 2.5' L x 2.5' W x 2 'D Oakite Liquid Rustripper – Vat size 2.5' L x 2.5' W x 2 'D Oakite Rustripper – Vat size 2.5' L x 2.5' W x 2 'D 	 Grit Blast Grit blasting using, Black Beauty, Garnet, Sand, Steel Shot, Walnut hulls, corn cobs and soda. Pressure Washing 	 Vats (for Component Cleaning) Caustic Cleaner (Cee-Bee J-84AL Liquid) – Vat size 10' L x 3.8' W x 4.5 'D Mild Alkaline (Cee-Bee Super Bee 300LF)) – Vat size 8' L x 3.8' W x 4.5 'D Protective Coating (Cee-Bee MX-15U) - Vat size 8' L x 3.8' W x 4.5 'D Deoxidizer (Cee-Bee C-623) - Vat size 8' L x 3.8' W x 4.5 'D Passivation Solution (HNO3) – Vat Size 8' L x 3.8' W x 4.5 'D

Onsite Cleaning

	WSTF	MSFC	SSC
Tank		Mid-Strength 300 Series (Non-	Mid-Strength 300 Series (Non-
Lines		Magnetic) Stainless Steel	Magnetic) Stainless Steel
Lines		(24'Lx5'Wx10'D	1. Degrease
		 Aqueous Degrease 	2. DI Water Rinse
		2. Rinse	Caustic cleaner
		Pickle (micro etch) –	4. DI Water Rinse
		Nitric/Hydrofluoric Acid	Deoxider – if required
		4. Rinse	6. DI Water Rinse
		Passivation – Nitric Acid	Mild Alkaline
		6. Rinse	8. DI Water Rinse
		Hot Water Rinse	Passivation -Nitric Acid
		8. Precision Cleaning	10. Mild Alkaline
		_	11. DI Water Rinse
		Aluminum Cleaning Process	
		(24'Lx5'Wx10'D	Aluminum Cleaning Process
			1. Degrease
		Aqueous Degrease	2. DI Water Rinse
		2. Rinse	3. Deoxider – if required
		3. [Steps a, b, c, and d at least once,	4. DI Water Rinse
		but repeated as necessary, or to	5. Protective Coating-if required
		specification]	6. DI Water Rinse
		a. Tri-Acid Deoxidizer	
		b. Rinse	Carbon Steel (Magnetic) Cleaning
		c. Caustic Etch	Process
		d. Rinse	1. Degrease
		4. Chromate Conversion Coating	2. DI Water Rinse
		5. Rinse	Caustic cleaner
		6. Hot Water Rinse	4. DI Water Rinse
		7. Precision Cleaning	5. Deoxider – if required
			6. DI Water Rinse
		Carbon Steel (Magnetic) Cleaning	7. Mild Alkaline
		Process (16'Lx5'Wx8'D	8. DI Water Rinse
			7. Protective Coating
		Aqueous Degrease	
		2. Rinse	
		3. Mild Steel Pickle – Sulfuric Acid	
		4. Rinse	
		5. Iron Phosphate	
		6. Rinse	
		7. Hot Water Rinse	
		8. Precision Cleaning	
		DI	
Other	Very long lines	DI water facility	DI Water Plant
	Large pressure vessels	Large Hardware	

Documentation

	WSTF	MSFC	SSC
Surface Cleanliness	SN-C-0005, "Contamination	SN-C-0005, "Contamination	SSTD-8070-0089-FLUIDS,
	Control Requirements for the	Control Requirements for the	"John C. Stennis Space
	Space Shuttle Program"	Space Shuttle Program"	Center
		IEST-STD-CC1246, "Product	Surface Cleanliness
	JPR 5322.1, "Contamination	Cleanliness Levels and	Requirements
	Control Requirements Manual"	Contamination Control	For SSC Fluid Systems"
		Program"	
Center Procedures	WJI-SVC-CSS-0092, "General	MSFC-SPEC-164, "Cleanliness	STP-8810-0005, "John C.
	Component Precision Cleaning	of components for use in	Stennis Space Center
	and Cleanliness Verification"	Oxygen, Fuel, and Pneumatic	Technical Procedure
		Systems"	For Clean Line Cleaning"
	WJI-SVC-CSS-0030,	MSFC-PROC-166, "Hydraulic	
	"Precleaning of Hardware,	System Detailed Parts,	STP-8810-0019, "John C.
	Components, and Assemblies to a	Components, Assemblies, and	Stennis Space Center
	Visibly Clean Level"	Hydraulic Fluids for Space	Technical Procedure
		Vehicles, Cleaning, Testing, and	For Cleaning Verification"
	WJI-SVC-CSS-0032, "Final	Hauling"	
	Cleaning and Cleanliness		
	Verification of Hardware in the		
	Class 100 Clean Room"		

Table I. Classification of Cleanliness Levels Requirements

	A. Particulate Contaminatio	n Levels	Con	B. NVR tamination Levels	C. Visib	le Contamination Levels
	Particle Size Range	Maximum Number of Particles per 0.1		Maximum Quantity of NVR (mg per		
Level	(micrometer)	m ² *	Level	0.1m ²⁾	Level	Definition
25	<5 5 to 15 >15 to 25 >25	Unlimited 19 14 0	A	1	GC	Generally Clean. Freedom from manufacturing residue, dirt, oil,
50	<15 15 to 25 >25 to 50 >50	Unlimited 17 8 0	В	2		grease, etc. The GC level should therefore be specified for hardware that is not
100	<25 25 to 50 >50 to 100 >100	Unlimited 68 11 0	С	3		sensitive to contamination and is easily cleaned or recleaned.
150	<50 50 to 100 >100 to 150 >150	Unlimited 47 5 0	D	4	VC	Visibly Clean. Free all particulate and nonparticulate matter visible to the normal
200	<50 50 to 100 >100 to 200 >200	Unlimited 154 16 0	E	5		unaided eye or corrected vision eye. This level is for hardware that
250	<100 100 to 200 >200 to 250 >250	Unlimited 39 3 0	F	7		requires removal of surface particulate and nonparticulate for operation; or
300	<100 100 to 250 >250 to 300 >300	Unlimited 93 3 0	G	10		hardware for which recleaning would be difficult and/or time- consuming.
500	<100 100 to 250 >250 to 500 >500	Unlimited 1073 27 0	Н	15	VC+UV	Visibly Clean + Ultraviolet. Visually clean and inspected with ultraviolet light.
750	<250 250 to 500 >500 to 750 >750	Unlimited 205 9 0	J	25		This level is usually specified for hardware that cannot tolerate buildup of
1000	<500 500 to 750 >750 to 1000 >1000	Unlimited 34 5 0				hydrocarbons between uses or operations.
*No silti	ng permitted					

("Process Specification for Cleaning of Hardware"/PRC-5001, Rev. E [JSC], page 20)

	PARTICULATE LEVELS		NVR LEVELS	
CLASS	PARTICLE SIZE IN MICRONS		LEVEL	MAXIMUM mg/0.1 m ²
1	>2500	0	A	
	700 <x<2500< td=""><td>1</td><td></td><td></td></x<2500<>	1		
	175 <x<700< td=""><td>5</td><td></td><td></td></x<700<>	5		
	NO SILTING			
			В	5
Ш	>1000	0		
	NO SILTING			
1119	>800	0		
	NO SILTING	-		
IV	>400	0		
	NO SILTING	•		
v	VISUALLY CLEA	N/NO SILTING		

(Cleaning Specification MSFC-164-B)